

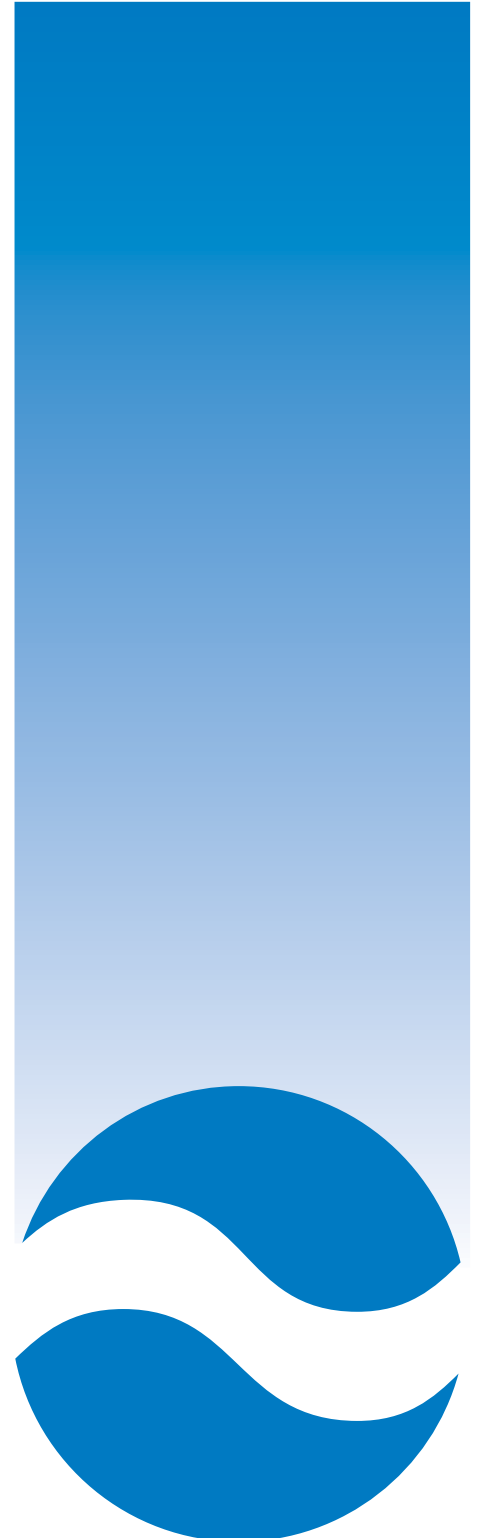
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JOINT INDUSTRY STANDARD

Requirements for
Soldering Pastes



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- Include a feedback system on use and problems for future improvement

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IPC J-STD-005A

Requirements for Soldering Pastes

A standard developed by the Solder Paste Task Group (5-24b)
of the Assembly and Joining Committee (5-20) of IPC

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Users of this publication are encouraged to participate in the
development of future revisions.

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